

TOSHIBA Rectifier Silicon Diffused Type

CMG03

General-Purpose Rectifier Applications

- Average forward current: $I_F (AV) = 1.0 \text{ A}$
- Repetitive peak reverse voltage: $V_{RRM} = 600 \text{ V}$
- Peak forward voltage: $V_{FM} = 1.1 \text{ V (max.)}$
- Suitable for high-density board assembly due to the use of a small surface-mount package, M-FLAT™

Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

| Characteristics | Symbol | Rating | Unit |
|-----------------------------------|------------|------------|------|
| Repetitive peak reverse voltage | V_{RRM} | 600 | V |
| Average forward current | $I_F (AV)$ | 1.0(Note1) | A |
| Non-repetitive peak surge current | I_{FSM} | 80 (50 Hz) | A |
| Junction temperature | T_j | -40 to 150 | °C |
| Storage temperature | T_{stg} | -40 to 150 | °C |

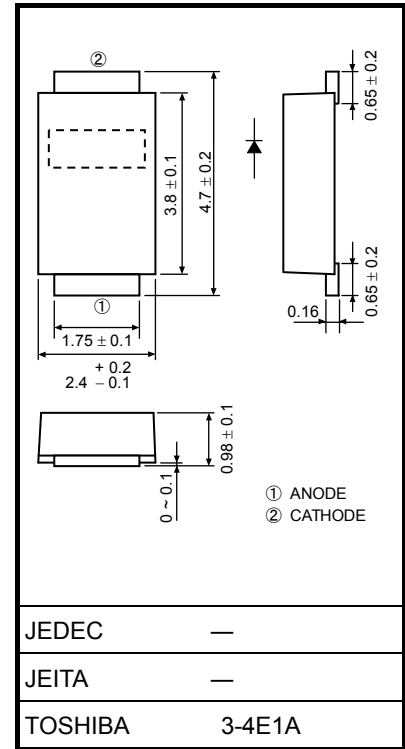
Note 1: $T_l = 106^\circ\text{C}$

Device mounted on a ceramic board
 board size: 50 mm × 50 mm
 soldering land: 2 mm × 2 mm
 board thickness: 0.64 mm
 Half-sine waveform: $\alpha = 180^\circ$

Note 2: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Unit: mm



Weight: 0.023 g (typ.)

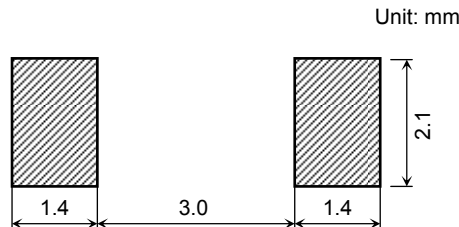
Electrical Characteristics (Ta = 25°C)

| Characteristics | Symbol | Test Condition | Min | Typ. | Max | Unit |
|---|----------------------|--|-----|------|-----|------|
| Peak forward voltage | V _{FM(1)} | I _{FM} = 1.0 A (Pulse test) | — | 0.88 | — | V |
| | V _{FM(2)} | I _{FM} = 2.0 A (Pulse test) | — | 0.92 | 1.1 | V |
| Peak repetitive reverse current | I _{RRM} | V _{RRM} = 400 V (Pulse test) | — | — | 10 | μA |
| Thermal resistance (junction to ambient) | R _{th(j-a)} | Device mounted on a ceramic board (board size: 50 mm × 50 mm) (soldering land: 2 mm × 2 mm) (board thickness: 0.64 mm) | — | — | 60 | °C/W |
| | | Device mounted on a glass-epoxy board (board size: 50 mm × 50 mm) (soldering land: 6 mm × 6 mm) (board thickness: 1.6 mm) | — | — | 110 | |
| | | Device mounted on a glass-epoxy board (board size: 50 mm × 50 mm) (soldering land: 2.1 mm × 1.4 mm) (board thickness: 1.6 mm) | — | — | 180 | |
| Thermal resistance (junction to lead) | R _{th(j-l)} | — | — | — | 16 | °C/W |

Marking

| Abbreviation Code | Part No. |
|-------------------|----------|
| G3 | CMG03 |

Standard Soldering Pad



Handling Precaution

The absolute maximum ratings denote the absolute maximum ratings, which are rated values and must not be exceeded during operation, even for an instant. The following are the general derating methods that we recommend when you design a circuit with a device.

V_{RRM} : We recommend that the worst case voltage, including surge voltage, be no greater than 80% of the absolute maximum rating of V_{RRM} for a DC circuit and be no greater than 50% of that of V_{RRM} for an AC circuit.

V_{RRM} has a temperature coefficient of 0.1%/°C. Take this temperature coefficient into account designing a device at low temperature.

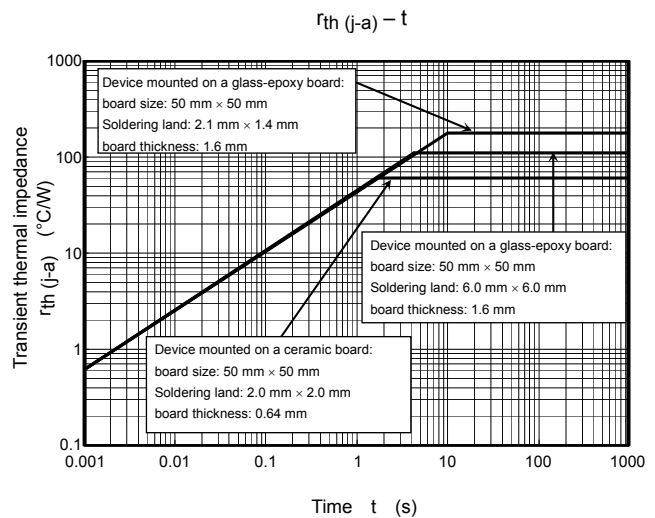
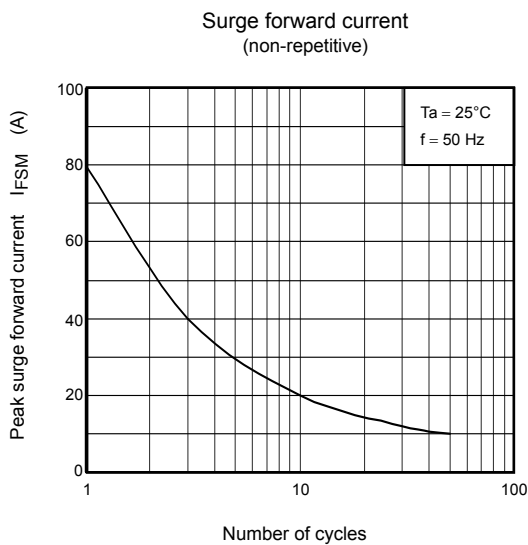
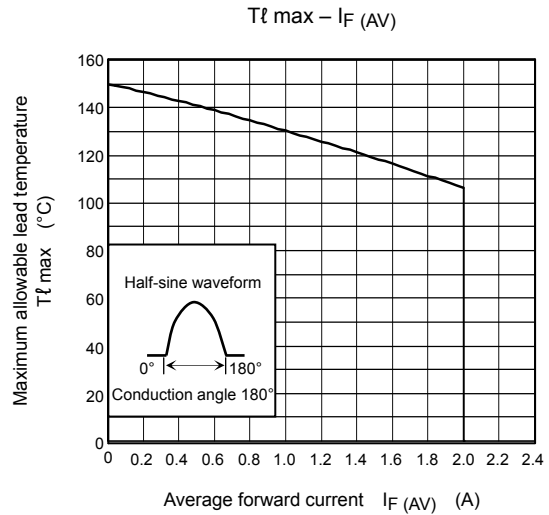
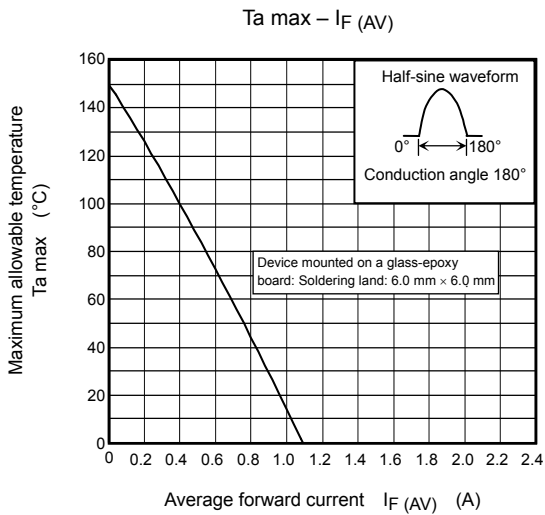
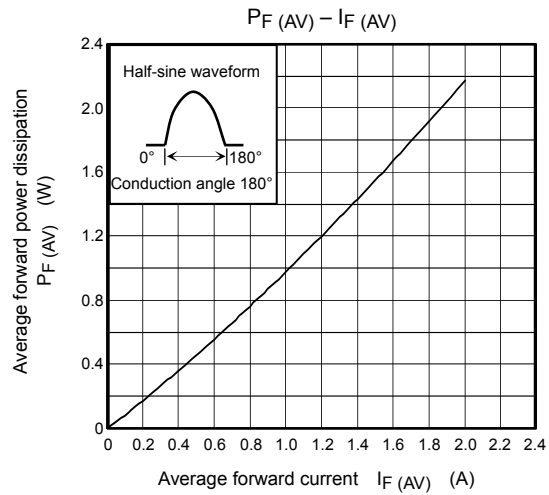
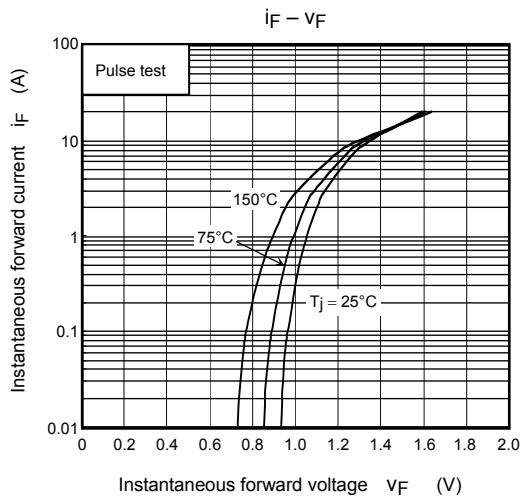
$I_{F(AV)}$: We recommend that the worst case current be no greater than 80% of the absolute maximum rating of $I_{F(AV)}$. Carry out adequate heat design. If you can't design a circuit with excellent heat radiation, set the margin by using an allowable T_{max} - $I_{F(AV)}$ curve.

This rating specifies the non-repetitive peak current in one cycle of a 50-Hz sine wave, condition angle 180. Therefore, this is only applied for an abnormal operation, which seldom occurs during the lifespan of the device.

We recommend that a device be used at T_j below 120°C under the worst load and heat radiation conditions.

Thermal resistance between junction and ambient fluctuates depending on the device's mounting condition. When using a device, design a circuit board and a soldering land size to match the appropriate thermal resistance value.

Please refer to the Rectifiers databook for further information.



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20070701-EN GENERAL

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